



GP/2826
PATENT

Case Docket No. MICRON.240A

Date: January 6, 2003

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In re application of : Derraa et al.
App. No. : 09/944,903
Filed : August 30, 2001
For : HIGH ASPECT RATIO
CONTACT STRUCTURE
WITH REDUCED SILICON
CONSUMPTION
Examiner : Victor A. Mandala
Art Unit : 2826

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January 6, 2003

(Date)

Linda H. Liu, Reg. No. 51,244

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UNITED STATES PATENT AND TRADEMARK OFFICE
P.O. Box 2327
Arlington, VA 22202

ATTN: BOX NON-FEE AMENDMENT

Sir:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated as shown below:

CLAIMS AS FILED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
Total Claims	18	26	= 0 ×	\$18	= \$0
Independent Claims	2	3	= 0 ×	\$84	= \$0
If application has been amended to contain multiple dependent claim(s), then add				\$280	= \$0
Time Extension Fee					\$0
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0

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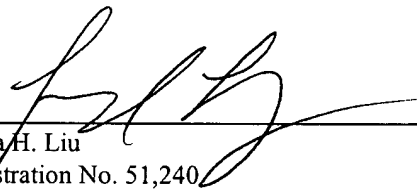
(X) Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.

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MICRON 240A



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE 1-15-03

#9
Amatt B
D Smalls - Leaper
PATENT

Applicant : Derraa et al.) Group Art Unit 2826
Appl. No. : 09/944,903)
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AMENDMENT

United States Patent and Trademark Office
P.O. Box 2327
Arlington, VA 22202

Dear Sir:

In response to the Office Action mailed October 4, 2002, please amend the above captioned application as follows:

IN THE CLAIMS:

Please amend the claims as follows:

1. (Amended) An integrated circuit, comprising:
- a silicon substrate;
 - an insulating layer formed on an upper surface of the substrate wherein a contact opening is formed in the insulating layer, wherein the contact opening extends from an upper surface of the insulating layer to the upper surface of the substrate;
 - a conductive contact deposited in the opening in a manner such that the conductive contact directly contacts the upper surface of the substrate, wherein the conductive